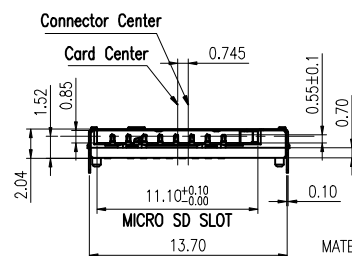
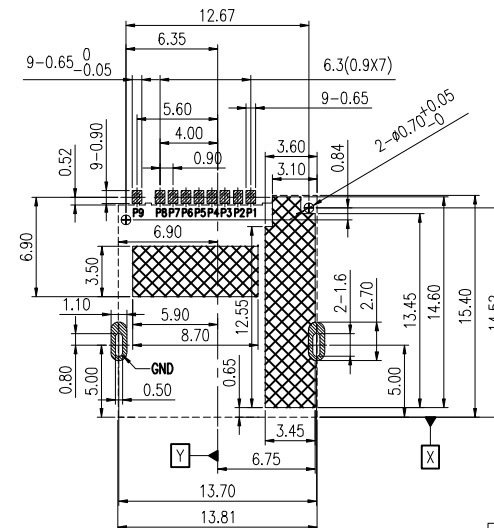
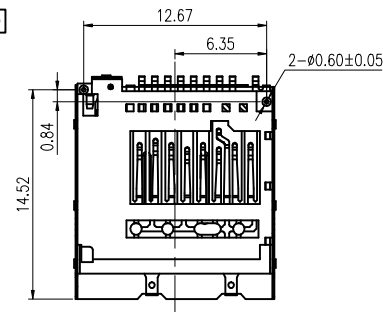
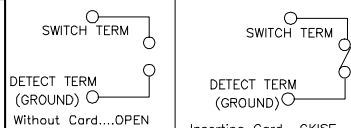
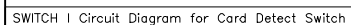


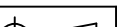
REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0	_____	NEW RELEASE	10/08'18	HFL	WZX	HAIYONG



MATERIAL:
1.1 INSULATOR:LCP E6808L UL94V-0 BLACK
1.2 CONTACTS: COPPER ALLOY C5210-EH ($t=0.10\pm0.01\text{mm}$)
GOLD 1u" Min PLATED ON CONTACT AREA SOLDER TAIL
Shell:SUS 304R-H ($t=0.10\pm0.01\text{mm}$)
2.ELECTRICAL:
2.1 CURRENT RATING:0.5A AC,DC
2.2 TEMPERATURE RANGE:-25 $\pm$ +85 $^{\circ}$ C.
2.3 INSULATION RESISTANCE:1000M Ω MIN(500V DC)
2.4CONTACT RESISTANCE:100M Ω MAX
2.5WITHSTANDING VOLTAGE:500V AC/MINUTE
3.PART MUST COMPLY TAI50L HF W/ND-3-I-091 SPECIFICATION



6	Slider	PA9T GP2450NH	Black	1		UL94V-0
5	Housing	LCP U6808L	Black	1		UL94V-0
4	Spring	SWP		1		
3	Link	SUS		1		
2	Contact	C5210-EH		1	Ni 50u Min" Au 1u"Min"	
1	Shell	SUS 304R-H		1	Ni 50u Min"	
NO	PART NAME	MATERIAL	COLOR	Number	FINISH	REMARKS

MILLIMETERS		INCH		UNITS		 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.					
X ⁺ ± 2'		X ⁺ ± 2'		MM							
.X ±0.30		.XX ±0.012		MAT'L		PART NUMBER:		TITLE:			
.XX ±0.20		.XXX ±0.008		SEE NOTES							
.XXX±0.10		.XXXX±0.004		FINISH		XB-102312532		Micro SD Push TOP MOUNT TYPE H2.04			
				SEE NOTES		APPD:		DWG NO.:			
				QTY		CHKD:		C-102312532-00			
				SEE NOTES		DR:		<table><tr><th>SCALE</th><th>SHEET</th><th>REV.</th></tr><tr><td>1:1</td><td>1/2</td><td>A0</td></tr></table>		SCALE	SHEET
SCALE	SHEET	REV.									
1:1	1/2	A0									